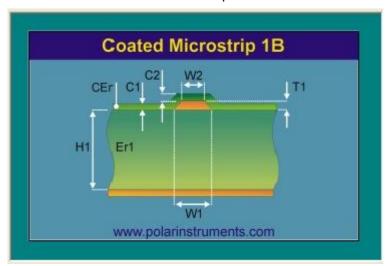
阻抗培训

1. 外层单端: Coated Microstrip 1B



Substrate 1 Height	H1	8.5000	+/- 0.0000 8.5000 8.5000
Substrate 1 Dielectric	Er1	4.2000	+/- 0.0000 4.2000 4.2000
Lower Trace Width	W1	7.0000	+/- 0.0000 7.0000 7.0000
Upper Trace Width	W2	6.0000	+/- 0.0000 6.0000 6.0000
Trace Thickness	T1	1.2000	+/- 0.0000 1.2000 1.2000
Coating Above Substrate	C1	1.0000	+/- 0.0000 1.0000 1.0000
Coating Above Trace	C2	1.0000	+/- 0.0000 1.0000 1.0000
Coating Dielectric	CEr	4.2000	+/- 0.0000 4.2000 4.2000
Impedance	Zo	0.00	0.00 0.00

H1: 介质厚度(PP片或者板材, 不包括铜厚)

Er1: PP片的介电常数(板材为: 4.5 P片4.2)

W1: 阻抗线上线宽(客户要求的线宽)

W2: 阻抗线下线宽(W2=W1-0.5MIL)

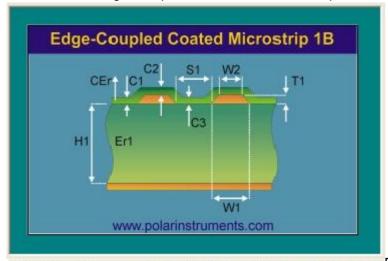
T1: 成品铜厚

C1: 基材的绿油厚度(我司按0.8MIL)

C2: 铜皮或走线上的绿油厚度(0.5MIL)

Cer: 绿油的介电常数(我司按3.3MIL)

2. 外层差分: Edge-Coupled Coated Microstrip 1B



Substrate 1 Height	H1	8.5000	+/- 0.0000	8.5000	8.5000
Substrate 1 Dielectric	Er1	4.2000	+/- 0.0000	4.2000	4.2000
Lower Trace Width	W1	7.0000	+/- 0.0000	7.0000	7.0000
Upper Trace Width	W2	6.0000	+/- 0.0000	6.0000	6.0000
Trace Separation	S1	8.0000	+/- 0.0000	8.0000	8.0000
Trace Thickness	T1	1.2000	+/- 0.0000	1.2000	1.2000
Coating Above Substrate	C1	1.0000	+/- 0.0000	1.0000	1.0000
Coating Above Trace	C2	1.0000	+/- 0.0000	1.0000	1.0000
Coating Between Traces	C3	1.0000	+/- 0.0000	1.0000	1.0000
Coating Dielectric	CEr	4.2000	+/- 0.0000	4.2000	4.2000
Differential Impedance	Zdiff	0.00	ſ	0.00	0.00

H1: 介质厚度(PP片或者板材, 不包括铜厚)

Er1: PP片的介电常数(板材为: 4.5 P片4.2)

W1: 阻抗线上线宽(客户要求的线宽)

W2: 阻抗线下线宽(W2=W1-0.5MIL)

S1: 阻抗线间距(客户原稿)

T1: 成品铜厚

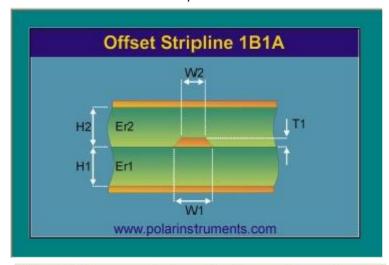
C1: 基材的绿油厚度(我司按0.8MIL)

C2: 铜皮或走线上的绿油厚度(0.5MIL)

C3: 基材上面的绿油厚度(0.50MIL)

Cer: 绿油的介电常数(我司按3.3MIL)

3. 内层单端: Offset Stripline 1B1A



Substrate 1 Height	H1	4.2500	+/- [0.0000	4.2500	4.2500
Substrate 1 Dielectric	Er1	4.2000	+/-	0.0000	4.2000	4.2000
Substrate 2 Height	H2	4.2500	+/-	0.0000	4.2500	4.2500
Substrate 2 Dielectric	Er2	4.2000	+/-	0.0000	4.2000	4.2000
Lower Trace Width	W1	7.0000	+/-	0.0000	7.0000	7.0000
Upper Trace Width	W2	6.0000	+/-	0.0000	6.0000	6.0000
Trace Thickness	T1	1.2000	+/-	0.0000	1.2000	1.2000
Impedance	Zo	0.0000		Г	0.0000	0.0000

H1: 介质厚度(PP片或者光板, 不包括铜厚) Er1: H1厚度PP片的介电常数(P片4. 2MIL) H2: 介质厚度(PP片或者光板, 不包括铜厚)

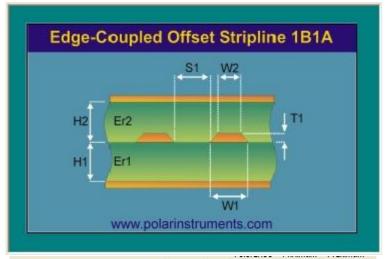
H2: 介质厚度(PP片或者光板, 不包括铜厚) Er2: H2厚度PP片的介电常数(P片4. 2MIL)

W1: 阻抗线上线宽(客户要求的线宽)

W2: 阻抗线下线宽(W2=W1-0.5MIL)

T1: 成品铜厚

4. 内层差分: Edge-Couled Offset Stripline 1B1A



Substrate 1 Height	H1	4.2500	+/-	0.0000	4.2500	4.2500
Substrate 1 Dielectric	Er1	4.2000	+/-	0.0000	4.2000	4.2000
Substrate 2 Height	H2	4.2500	+/-	0.0000	4.2500	4.2500
Substrate 2 Dielectric	Er2	4.2000	+/-	0.0000	4.2000	4.2000
Lower Trace Width	W1	7.0000	+/-	0.0000	7.0000	7.0000
Upper Trace Width	W2	6.0000	+/-	0.0000	6.0000	6.0000
Trace Separation	S1	8.0000	+/-	0.0000	8.0000	8.0000
Trace Thickness	T1	1.2000	+/-	0.0000	1.2000	1.2000
Differential Impedance	Zdiff	0.00			0.00	0.00

H1: 介质厚度(PP片或者光板, 不包括铜厚)

Er1: H1厚度PP片的介电常数(P片4. 2MIL)

H2: 介质厚度(PP片或者光板, 不包括铜厚)

Er2: H2厚度PP片的介电常数(P片4. 2MIL)

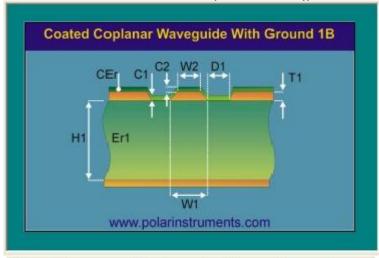
W1: 阻抗线上线宽(客户要求的线宽)

W2: 阻抗线下线宽(W2=W1-0.5MIL)

S1: 客户要求的线距

T1: 成品铜厚

5. 外层单端共面地: Coated Coplanar Waveguide With Ground 1B



Substrate 1 Height	H1	8.5000	+/- 0.0000 8.5000 8.5000
Substrate 1 Dielectric	Er1	4.2000	+/- 0.0000 4.2000 4.2000
Lower Trace Width	W1	7.0000	+/- 0.0000 7.0000 7.0000
Upper Trace Width	W2	6.0000	+/- 0.0000 6.0000 6.0000
Ground Strip Separation	D1	8.0000	+/- 0.0000 8.0000 8.0000
Trace Thickness	T1	1.2000	+/- 0.0000 1.2000 1.2000
Coating Above Substrate	C1	1.0000	+/- 0.0000 1.0000 1.0000
Coating Above Trace	C2	1.0000	+/- 0.0000 1.0000 1.0000
Coating Dielectric	CEr	4.2000	+/- 0.0000 4.2000 4.2000
Impedance	Zo	0.00	0.00 0.00

H1: 介质厚度(PP片或者板材, 不包括铜厚)

Er1: PP片的介电常数(板材为: 4.5 P片4.2)

W1: 阻抗线上线宽(客户要求的线宽)

W2: 阻抗线下线宽(W2=W1-0.5MIL)

D1: 阻抗线到两边铜皮的距离

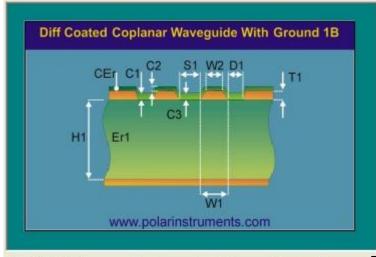
T1: 成品铜厚

C1: 基材的绿油厚度(我司按0.8MIL)

C2: 铜皮或走线上的绿油厚度(0.5MIL)

Cer: 绿油的介电常数(我司按3.3MIL)

6. 外层差分共面地: Diff Coated Coplanar Waveguide With Ground 1B



Substrate 1 Height	H1	8.5000	+/- 0.0000 8.5000 8.5000
Substrate 1 Dielectric	Er1	4.2000	+/- 0.0000 4.2000 4.2000
Lower Trace Width	W1	7.0000	+/- 0.0000 7,0000 7,0000
Upper Trace Width	W2	6.0000	+/- 0.0000 6.0000 6.0000
Trace Seperation	S1	8.0000	+/- 0.0000 8.0000 8.0000
Ground Strip Separation	D1	8.0000	+/- 0.0000 8.0000
Trace Thickness	T1	1.2000	+/- 0.0000 1.2000 1.2000
Coating Above Substrate	C1	1.0000	+/- 0.0000 1.0000 1.0000
Coating Above Trace	C2	1.0000	+/- 0.0000 1.0000 1.0000
Coating Between Traces	C3	1.0000	+/- 0.0000 1.0000 1.0000
Coating Dielectric	CEr	4.2000	+/- 0.0000 4.2000 4.2000
Differential Impedance	Zdiff	0.00	0.00

H1: 介质厚度(PP片或者板材, 不包括铜厚)

Er1: PP片的介电常数(板材为: 4.5 P片4.2)

W1: 阻抗线上线宽(客户要求的线宽)

W2: 阻抗线下线宽(W2=W1-0.5MIL)

S1: 阻抗线间距(客户原稿)

D1: 阻抗线到铜皮的距离

T1: 成品铜厚

C1: 基材的绿油厚度(我司按0.8MIL)

C2: 铜皮或走线上的绿油厚度(0.5MIL)

C3: 基材上面的绿油厚度(0.50MIL)

Cer: 绿油的介电常数(我司按3.3MIL)